



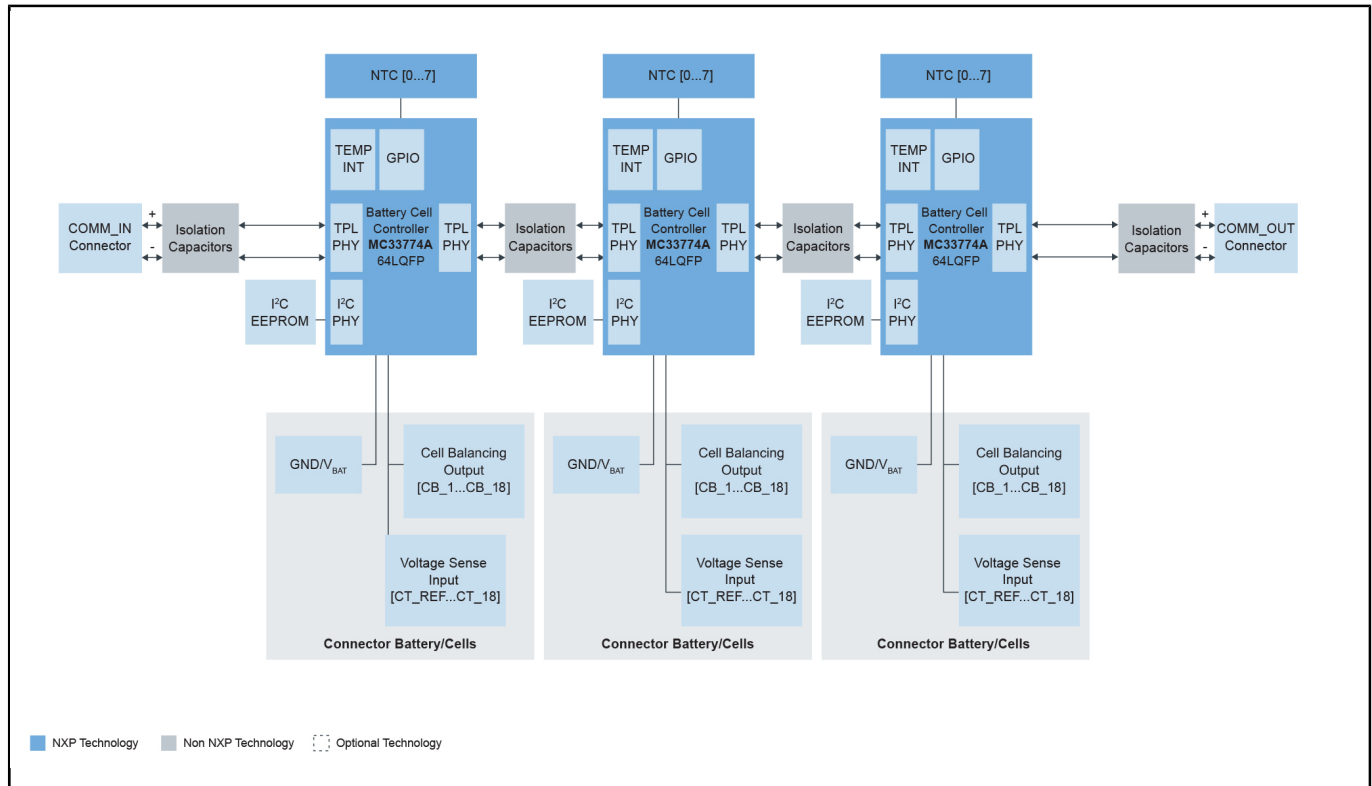
# 能够通过MC33774ATP进行ETPL通信的 HVBMS集中式电芯监测单元(CMU)

## RD33774PC3EVB

Last Updated: Apr 18, 2024

RD33774PC3EVB是具有电子传输协议链路(ETPL)通信的集中式芯片监测单元(CMU)参考设计。它是800V高压电池管理系统(HVBMS)硬件和软件快速原型制作的理想之选。该板还包含菊花链形式的3个MC33774模拟前端(AFE)。

# RD33774PC3EVB Block Diagram



View additional information for [能够通过MC33774ATP进行ETPL通信的HVBMS集中式电芯监测单元\(CMU\)](#).

**Note:** The information on this document is subject to change without notice.

**www.nxp.com**

NXP and the NXP logo are trademarks of NXP B.V. All other product or service names are the property of their respective owners. The related technology may be protected by any or all of patents, copyrights, designs and trade secrets. All rights reserved. © 2024 NXP B.V.